

PRODUCT NUMBER

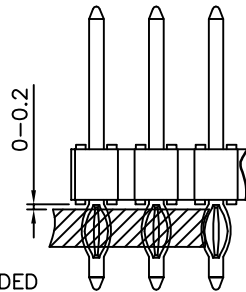
93690-YXX-XXLF

PLATING, SEE TABLE

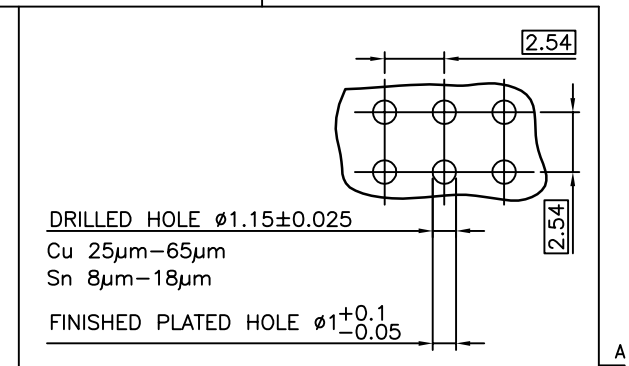
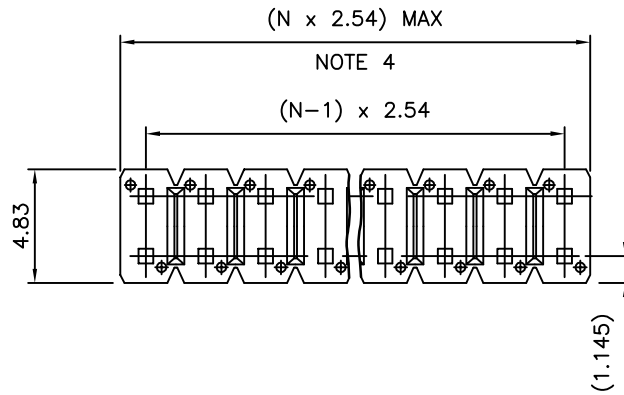
LEAD FREE
SEE NOTE 6 & 7

TOTAL NB OF POS
04 TO 72

PIN STYLE	DIM "A" REF	DIM "B" ±0.3	DIM "L" ±0.15
01	7.50	4.50	14.78
02	10.14	4.50	17.40
03	5.68	4.50	12.83
04	14.80	4.75	22.15
05	8.30	4.50	15.44
06	6.80	3.60	12.90
07	6.70	3.40	12.62
08	5.20	3.40	11.10
09	8.30	3.60	14.40
10	9.20	3.35	15.09

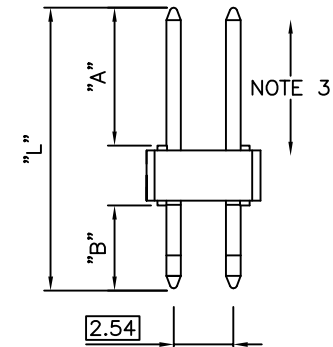
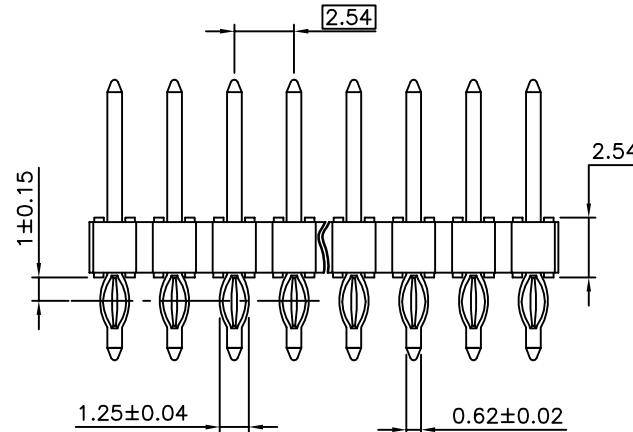


RECOMMENDED POSITION ON THE PCB



NOTES:

- HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC. UL94V-0 COLOR: BLACK
- PIN MATERIAL : COPPER ALLOY
- 9N MIN RETENTION IN EITHER DIRECTION
- TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS PER ROW, N x 2.54 = 20.32mm
- PACKAGING POLYBAGS OR BLIBOX
- LEAD FREE CONNECTOR
- "LF" MEANS THAT THE PRODUCT IS RoHS COMPLIANT THEN MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-47-0004



93690-7XX-XXLF	GOLD FLASH OVER 1.27µm Ni MIN	1.0µm TIN OVER 1.27µm Ni MIN
93690-5XX-XXLF	0.25µm GOLD/GXT OVER 1.27µm Ni MIN	1.0µm TIN OVER 1.27µm Ni MIN
93690-4XX-XXLF	3.05µm TIN OVER 1.27µm Ni MIN	
93690-1XX-XXLF	0.76µm GOLD/GXT OVER 1.27µm Ni MIN	1.0µm TIN OVER 1.27µm Ni MIN
PLATING	CONTACT AREA	PRESS FIT TAIL AREA

mat'l. code		surface		tolerance		projection		product family	
SEE NOTE		ISO 1302		ISO 406 ISO 1101		mm		BSTIK	
ltr	ecn no	dr	date	tolerances unless otherwise specified		mm		title	
R	B-18988	LMU	14.10.06	angles	linear	.x ±0.30	mm	HDR PRESS FIT DOUBLE ROW	
S	F-22590	AMA	15.11.23			.xx ±0.15			
						.xxx ±0.05	scale 5:1	dwg no	
L	F09-0043	JCO	09.05.07	dr	MULIN.L	99.06.30	FCJ	sheet 1 of 1 size	
M	F10-0229	LMU	10.10.04	engr	COMPAGNON J	99.06.30		93690 A3	
N	B16804	JCO	14.01.21	chr	NIZZI.P	99.06.30		type CUSTOMER Drawing	
P	B-17404	JCO	14.04.07	appd	JM.C	96.05.06			
sheet index	revision sheet								